



Reliability Report

Reliability Data for IXxx604SIA Series VIS Foundry Process
CU05UMS12010

**Report Title: Reliability Data for IXxx604SIA Series VIS Foundry
Process CU05UMS12010**

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**Reliability Report-IXxx604SIA Series VIS Foundry Process CU05UMS12010
Qualification No: 2010-015**

Introduction:

This report summarizes the Reliability data of Clare’s IXxx604SIA Series. The Reliability data presented here were collected during Clare’s product qualification. The purpose of this qualification was to verify the Clare’s Quality and Reliability requirements as outlined in Clare’s internal specifications. The IXxx604SIA Series Gate Driver silicon is founded at Vanguard International Semiconductor, Corp. (VIS) and assembled at Atec in the Philippines. The VIS process is CU05UMS12010.

Reliability Tests:

Table 1 below provides the qualification tests that were performed. The stress tests and sample size are chosen based on the Clare’s specification P-04-25-WW, “Reliability, Risk Analysis and Qualification Procedure” and with the approval of the product development team and quality assurance.

Table 1: Product Family IXxx604SIA Series Reliability Tests

Stress Test	Applicable Specs	Stress Conditions	Product/ Package	Number of Lots	Sample Size (SS)	Total SS
HAST	JESD22, A110-C	130°C, 85% 18.8PSI, 96hrs	IXDD604SIA SOIC – 8L	2	76	152
Thermal Shock (T/S)	Mil-Std-883, M1011	0 to 100°C, 10/10 dwells, 15 cycles	IXDD604SIA SOIC – 8L	3	55	165
Temp Cycle (T/C)	Mil-Std-883, N1010, “B”	-55 to 125°C, 10/10 dwells, 300 cycles	IXDD604SIA SOIC – 8L	3	55	165
High Temp Storage	JESD22-A103C	125°C, 1000hrs	IXDD604SIA SOIC – 8L	3	50	150
MSL	J-STD-020D.1	IR Reflow, Level 1	IXDD604SIA SOIC – 8L	3	50	150
ESD HBM	JESD22, A114-E	1.5kΩ, 100pF	IXDD604SIA SOIC – 8L	3	25	75

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Reliability Test Results:

The stress tests and associated results for the product family IXxx604SIA Series qualification are summarized in Table 2. The devices chosen for the qualification were from standard material manufactured through normal production test flow and electrically tested to datasheet limits prior to stressing. Then reliability stresses were conducted and electrically tested to datasheet limit at each interval and final readpoints.

Table 2: Product Family IXxx604SIA Series Reliability Test Results

Stress Test	Product/Kit Number	Readpoint / (Reject/ SS)	Comments
HAST	IXDD604SIA AV0001 0928 IXDD604 C00058 1023	96 hrs.	Qual Lot#1, #2 Data
		0/152	
Thermal Shock	IXDD604SIA AV0001 0928	15 Cycles	Qual Lot#1 Data
		0/55	
Thermal Shock	IXDD604SIA AV0002 0929	15 Cycles	Qual Lot#2 Data
		0/55	
Thermal Shock	IXDD604SIA AV0005 0944	15 Cycles	Qual Lot#3 Data
		0/55	
Temp Cycle	IXDD604SIA AV0001 0928	300 Cycles	Qual Lot#1 Data
		0/55	
Temp Cycle	IXDD604SIA AV0002 0929	300 Cycles	Qual Lot#2 Data
		0/55	
Temp Cycle	IXDD604SIA AV0005 0944	300 Cycles	Qual Lot#3 Data
		0/55	
High Temp Storage	IXDD604SIA AV0001 0928	1000 hrs.	Qual Lot#1 Data
		0/50	

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Stress Test	Product/Kit Number	Readpoint / (Reject/ SS)	Comments
High Temp Storage	IXDD604SIA AV0002 0929	1000 hrs.	Qual Lot#2 Data
		0/50	
High Temp Storage	IXDD604SIA AV0005 0944	1000 hrs.	Qual Lot# 3 Data
		0/50	
MSL	IXDD604SIA AV0001 0928	IR Reflow Level 1	Qual Lot#1 Data
		0/50	
MSL	IXDD604SIA AV0002 0929	IR Reflow Level 1	Qual Lot#2 Data
		0/50	
MSL	IXDD604SIA AV0005 0944	IR Reflow Level 1	Qual Lot#3 Data
		0/50	

ESD Testing Results:

As part of this qualification, the product family IXxx604SIA Series was subjected to Human Body Model (HBM) ESD Sensitivity Classification testing using a KeyTek Zapmaster system. The results are summarized in Table 3. All samples were electrically tested to data sheet limits before and after ESD stressing and they passed after +/-3000V zapping.

Table3: Product Family IXxx604SIA Series ESD Characterization Results

ESD Model	Product/Kit Number	Package	ESD Test Spec	RC Network	Highest Passed	Class
HBM	IXDD604SIA C00058	SOIC – 8L	JESD22, A114-E	1.5kΩ, 100pF	3000V	2

FIT (Failure in Time) Rate on the Product Family IXxx604SIA Series:

Table 4 summarizes the number of devices used for the product family IXxx604SIA Series reliability stress with associated failures. Using the HAST data, FITs were calculated based on the Acceleration Factor (AF) and equivalent device hours at 0.7eV of activation energy according to Clare’s procedure P-04-25-WW for 130°C test temperature and 40°C use temperatures. The calculated FITs from the reliability stress came out to be 44.03 for HAST.

Table 4: Product Family IXxx604SIA Series FIT Rate Summary

Qual#	Stress	Product/Kit Number	# of Devices	# of Fails	Hours Tested	Act. Energy	Acc. Factor	Equivalent Dev. Hours	FIT Rate @ 60% CL
1	HAST	IXDD604SIA AV0001 0928 IXDD604SIA C00058 1023	152	0	96	0.7	1.4318E +03	20,892,615	44.03

Conclusion:

The qualification of the product family IXxx604SIA Series has been successfully completed for the production release. The reliability and process data for VIS CU05UMS12010 can be found at S:/REED/Projects/New Process Information/Vanguard.

APPROVAL:

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